

RX3P07BBH

Nch 100V 80A Power MOSFET

V _{DSS}	100V
R _{DS(on)} (Max.)	8.4mΩ
I _D	±80A
P_{D}	89W

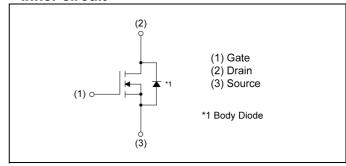
Outline



Features

- 1) Low on resistance
- 2) High power small mold package (TO220AB)
- 3) Pb-free plating; RoHS compliant
- 4) 100% UIS tested

•Inner circuit



Application

Switching

Packaging specifications

	Packing	Tube
Turno	Quantity (pcs)	1000
Type	Taping code	C16
	Marking	RX3P07BBH

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Parar	Symbol	Value	Unit	
Drain - Source voltage	V_{DSS}	100	V	
Continuous dusin suument	Silicon limit (V _{GS} =10V)	I _D *1	±80	Α
Continuous drain current	T _c = 25°C (V _{GS} =10V)	I _D *2	±70	Α
Pulsed drain current	I _{DP} *3	±320	Α	
Gate - Source voltage	V_{GSS}	±20	V	
Avalanche current, single pu	l _{AS} *4	23	Α	
Avalanche energy, single pu	E _{AS} *4	43	mJ	
Power dissipation		P _D *2	89	W
Junction temperature		T _j	150	°C
Operating junction and stora	T _{stg}	-55 to +150	°C	

●Thermal resistance

Parameter	Symbol	Values			Lloit
		Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC} *2	-	-	1.4	°C/W

● Electrical characteristics (T_a = 25°C)

Doromotor	Symbol	Conditions	Values			Lleit	
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = 1mA$	100	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I _D = 1mA referenced to 25°C	-	62.3	-	mV/°C	
Zero gate voltage drain current	I _{DSS} V _{DS} = 100V, V _{GS} = 0V		-	-	5	μA	
Gate - Source leakage current	I_{GSS} $V_{GS} = \pm 20V, V_{DS} = 0V$		-	-	±500	nA	
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 1mA$	2.0	-	4.0	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I _D = 1mA referenced to 25°C	-	-4.5	-	mV/°C	
Static drain - source	D *5	V _{GS} = 10V, I _D = 70A	-	6.5	8.4	O	
on - state resistance	R _{DS(on)} *5	V _{GS} = 6V, I _D = 35A	-	8.0	12.0	mΩ	
Gate resistance	R _G -		-	0.9	-	Ω	
Forward Transfer Admittance	Y _{fs} *5	V _{DS} = 5V, I _D = 35A	24	-	-	S	

^{*1} Limited by silicon chip capability.

^{*2} T_c =25°C, Limited only by maximum temperature allowed.

^{*3} Pw \leq 10µs, Duty cycle \leq 1%

^{*4} L \simeq 0.1mH, V_{DD} = 50V, R_G = 25 Ω , Starting T_j = 25 $^{\circ}$ C Fig.3-1,3-2

^{*5} Pulsed

● Electrical characteristics (T_a = 25°C)

Dorameter	Symbol	Conditions		Unit			
Parameter	Symbol Conditions —		Min.	Тур.	Max.	Urill	
Input capacitance	C _{iss}	V _{GS} = 0V	-	2410	-		
Output capacitance	C _{oss}	V _{DS} = 50V	-	460	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	20	-		
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq 50V, V_{GS} = 10V$	1	24	ı		
Rise time	t r*5	I _D = 35A	1	25	ı	no	
Turn - off delay time	t _{d(off)} *5	R _L ≃ 1.42Ω	-	58	-	ns	
Fall time	t _f *5	$R_G = 10\Omega$	-	29	-		

• Gate charge characteristics $(T_a = 25^{\circ}C)$

Doromotor	Cymah al	Conditions		Values			l limit		
Parameter	Symbol			Min.	Тур.	Max.	Unit		
Total gate charge	O *5	O *5	V _{GS} = 10V	-	38.0	-			
Total gate charge	Q _g *5		$V_{DD} \simeq 50V$	V _{DD} ≈ 50V		-	25.0	-	" C
Gate - Source charge	Q _{gs} *5	I _D = 50A	V _{GS} = 6V	-	8.5	-	nC		
Gate - Drain charge	Q _{gd} *5			-	9.8	-			

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Continuous forward current	I _S	T _a = 25°C	1	-	70	Α
Pulse forward current	I _{SP} *3	1 _a - 25 C	-	-	320	Α
Forward voltage	V _{SD} *5	$V_{GS} = 0V, I_{S} = 70A$	-	-	1.2	V
Reverse recovery time	t _{rr} *5	I _S = 50A, V _{GS} =0V	-	63	-	ns
Reverse recovery charge	Q _{rr} *5	di/dt = 100A/μs	-	125	1	nC

Fig.1 Power Dissipation Derating Curve

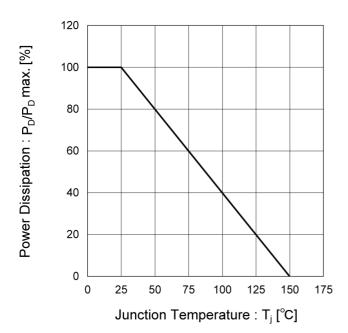
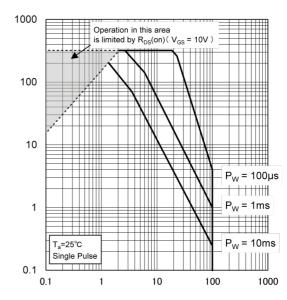


Fig.2 Maximum Safe Operating Area



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

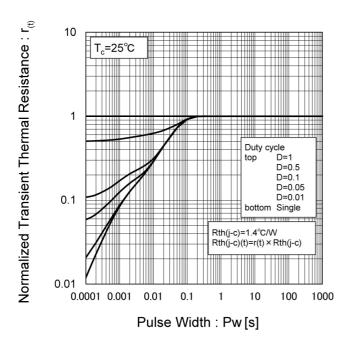


Fig.4 Single Pulse Maximum Power Dissipation

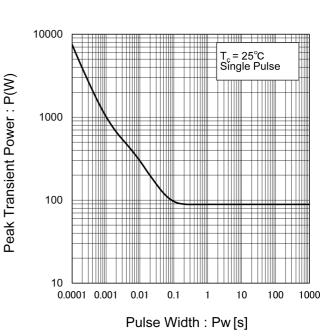


Fig.5 Typical Output Characteristics(I)

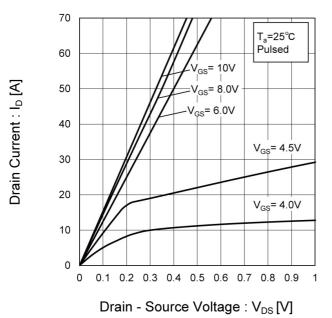
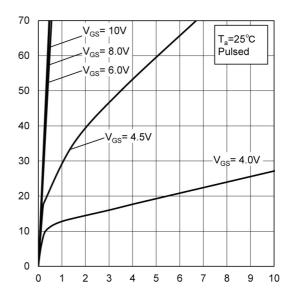


Fig.6 Typical Output Characteristics(II)



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.7 Breakdown Voltage vs.

Junction Temperature

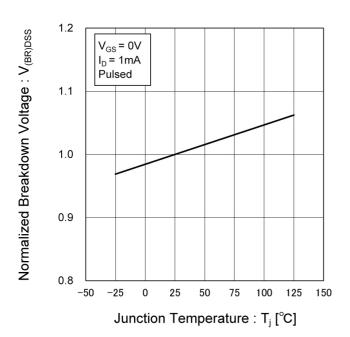
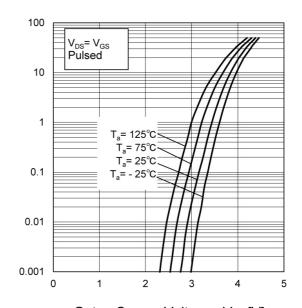


Fig.8 Typical Transfer Characteristics



Gate - Source Voltage : $V_{GS}[V]$

Drain Current : I_D [A]

Fig.9 Gate Threshold Voltage vs.
Junction Temperature

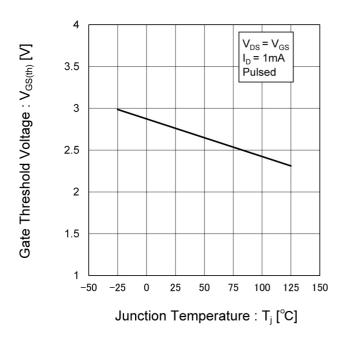


Fig.10 Forward Transfer Admittance vs.
Drain Current

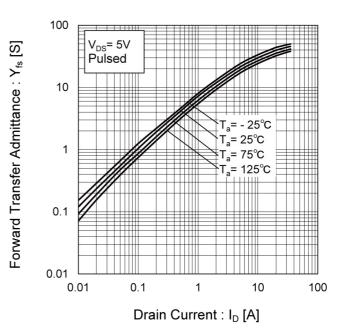


Fig.11 Drain Current Derating Curve

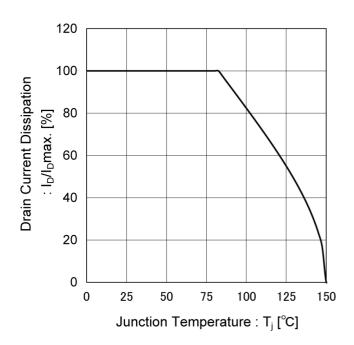


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

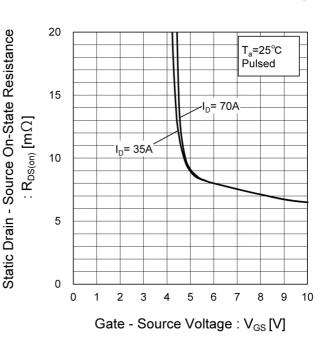


Fig.13 Static Drain - Source On - State
Resistance vs. Junction Temperature

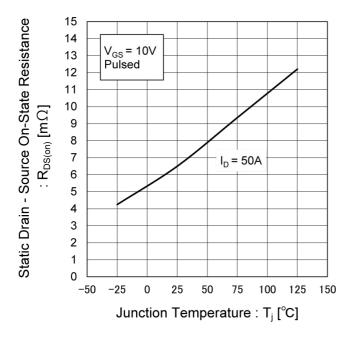


Fig.14 Static Drain - Source On - State
Resistance vs. Drain Current (I)

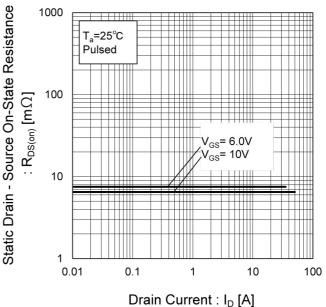


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

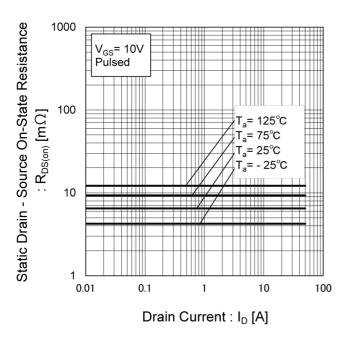


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

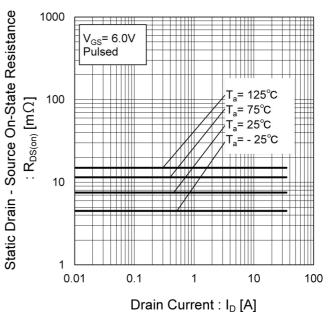


Fig.17 Typical Capacitances vs.

Drain - Source Voltage

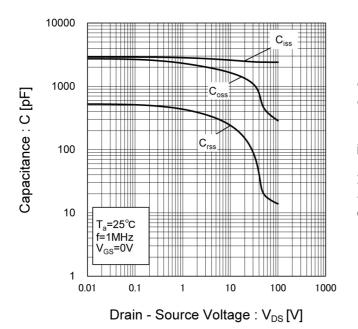


Fig.18 Switching Characteristics

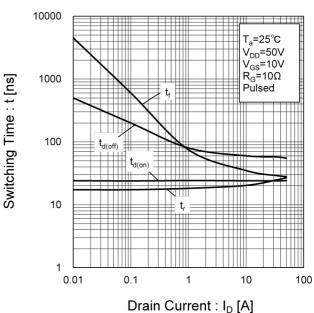


Fig.19 Typical Gate Charge

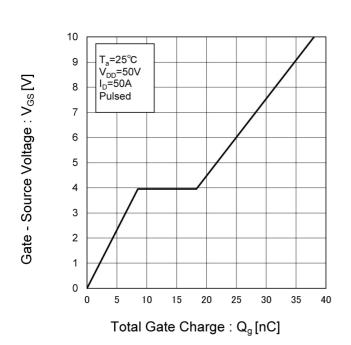
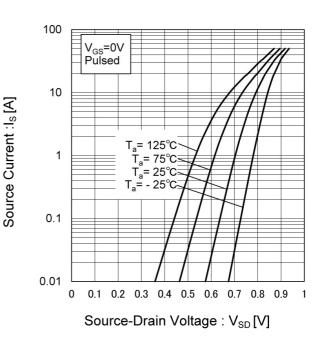


Fig.20 Source Current vs.

Source Drain Voltage



Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

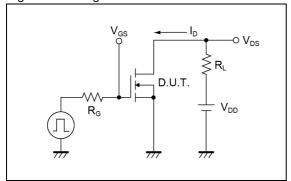


Fig.1-2 Switching Waveforms

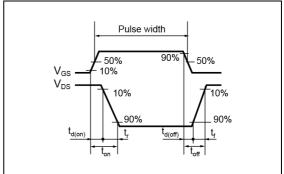


Fig.2-1 Gate Charge Measurement Circuit

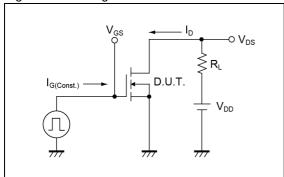


Fig.2-2 Gate Charge Waveform

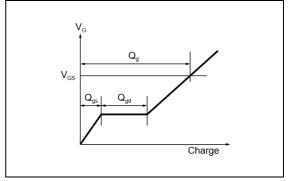


Fig.3-1 Avalanche Measurement Circuit

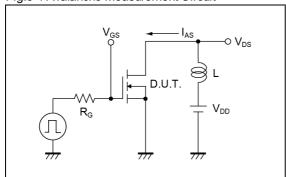
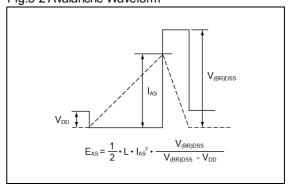
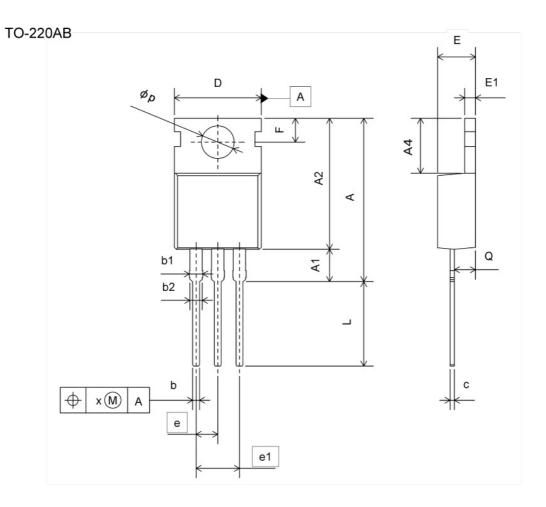


Fig.3-2 Avalanche Waveform



Dimensions



DIM	MILIME	TERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	18.30	20.00	0.720	0.787
A1	3.60	4.00	0.142	0.157
A2	14.70	16.00	0.579	0.630
A4	6.30	6.60	0.248	0.260
b	0.65	0.95	0.026	0.037
b1	1.20	1.75	0.047	0.069
b2	1.20	1.70	0.047	0.067
С	0.35	0.65	0.014	0.026
D	9.96	10.36	0.392	0.408
E	4.24	4.64	0.167	0.183
E1	1.14	1.40	0.045	0.055
е	2.	54	0.1	00
e1	5.	80	0.2	200
F	2.60	3.00	0.102	0.118
L	9.47	10.37	0.373	0.408
ϕ p	3.69	3.99	0.145	0.157
Q	2.30	2.70	0.091	0.106
х	-1	0.38	_	0.015

Dimension in mm/inches



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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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